BFR92A NPN 5 GHz wideband transistor Rev. 04 – 2 March 2009

Product data sheet

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NXP Semiconductors



FEATURES

- High power gain
- Low noise figure
- Low intermodulation distortion.

APPLICATIONS

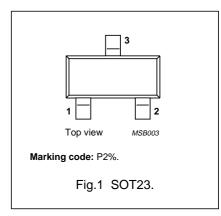
• RF wideband amplifiers and oscillators.

DESCRIPTION

NPN wideband transistor in a plastic SOT23 package. PNP complement: BFT92.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage		-	20	V
V _{CEO}	collector-emitter voltage		-	15	V
I _C	collector current (DC)		-	25	mA
P _{tot}	total power dissipation	$T_s \le 95 \ ^{\circ}C$	-	300	mW
C _{re}	feedback capacitance	$I_{C} = i_{c} = 0; V_{CE} = 10 V; f = 1 MHz$	0.35	_	pF
f _T	transition frequency	I _C = 15 mA; V _{CE} = 10 V; f = 500 MHz	5	_	GHz
G _{UM}	maximum unilateral power gain	I_{C} = 15 mA; V_{CE} = 10 V; f = 1 GHz; T_{amb} = 25 °C	14	-	dB
		I_{C} = 15 mA; V_{CE} = 10 V; f = 2 GHz; T_{amb} = 25 °C	8	-	dB
F	noise figure	$I_C = 5 \text{ mA}; V_{CE} = 10 \text{ V}; \text{ f} = 1 \text{ GHz};$ $\Gamma_s = \Gamma_{opt}; T_{amb} = 25 \text{ °C}$	2.1	-	dB
Vo	output voltage		150	-	mV

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	20	V
V _{CEO}	collector-emitter voltage	open base	-	15	V
V _{EBO}	emitter-base voltage	open collector	_	2	V
I _C	collector current (DC)		_	25	mA
P _{tot}	total power dissipation	$T_s \le 95 \text{ °C}$; note 1; see Fig.3	-	300	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	$T_s \le 95 \ ^{\circ}C$; note 1	260	K/W

Note

1. T_s is the temperature at the soldering point of the collector pin.

CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector leakage current	I _E = 0; V _{CB} = 10 V	_	_	50	nA
h _{FE}	DC current gain	$I_{C} = 15 \text{ mA}; V_{CE} = 10 \text{ V}; \text{ see Fig.4}$	65	90	135	
C _c	collector capacitance	$I_E = i_e = 0$; $V_{CB} = 10$ V; f = 1 MHz; see Fig.5	-	0.6	_	pF
C _e	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 10 V; f = 1 MHz$	-	1.2	-	pF
C _{re}	feedback capacitance	$I_{C} = i_{c} = 0; V_{CE} = 10 V; f = 1 MHz$	-	0.35	-	pF
f _T	transition frequency	$I_C = 15 \text{ mA}; V_{CE} = 10 \text{ V}; f = 500 \text{ MHz};$ see Fig.6	-	5	-	GHz
G _{UM}	maximum unilateral power gain (note 1)	I_{C} = 15 mA; V _{CE} = 10 V; f = 1 GHz; T _{amb} = 25 °C	-	14	-	dB
		I_{C} = 15 mA; V _{CE} = 10 V; f = 2 GHz; T _{amb} = 25 °C	-	8	-	dB
F	noise figure	$\label{eq:lc} \begin{array}{l} I_C = 5 \text{ mA; } V_{CE} = 10 \text{ V; } f = 1 \text{ GHz;} \\ \Gamma_s = \Gamma_{opt}; \ensuremath{T_{amb}} = 25 \ensuremath{^\circ C}; \\ \text{see Figs 13 and 14} \end{array}$	-	2.1	-	dB
		$\label{eq:lc} \begin{array}{l} I_C = 5 \text{ mA; } V_{CE} = 10 \text{ V; } f = 2 \text{ GHz;} \\ \Gamma_s = \Gamma_{opt}; \ T_{amb} = 25 \ ^\circ\text{C}; \\ \text{see Figs 13 and 14} \end{array}$	-	3	-	dB
Vo	output voltage	notes 2 and 3	_	150	-	mV
d ₂	second order intermodulation distortion	notes 2 and 4; see Fig.16	-	-50	-	dB

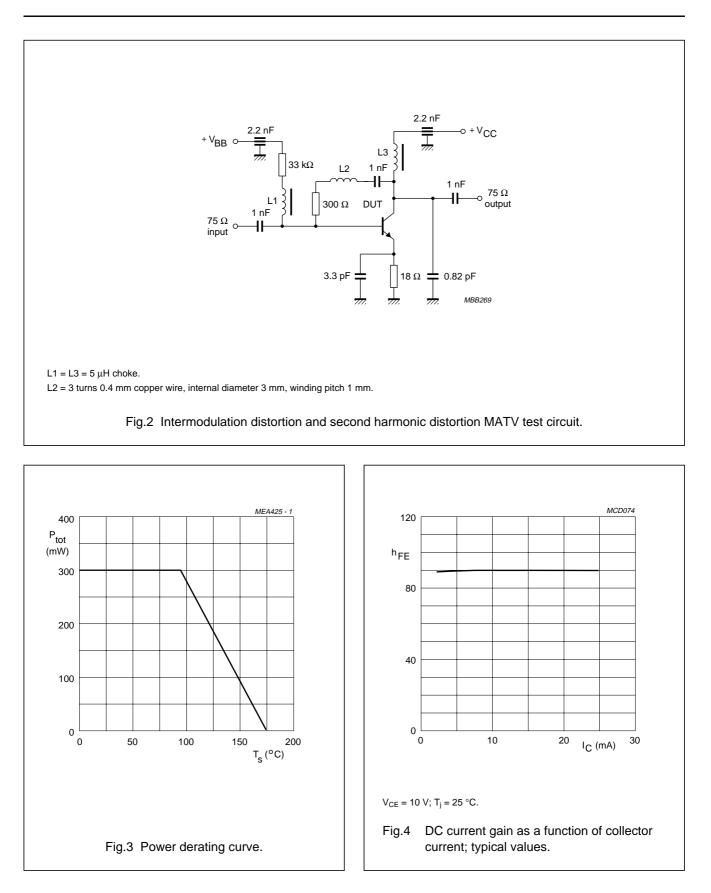
Notes

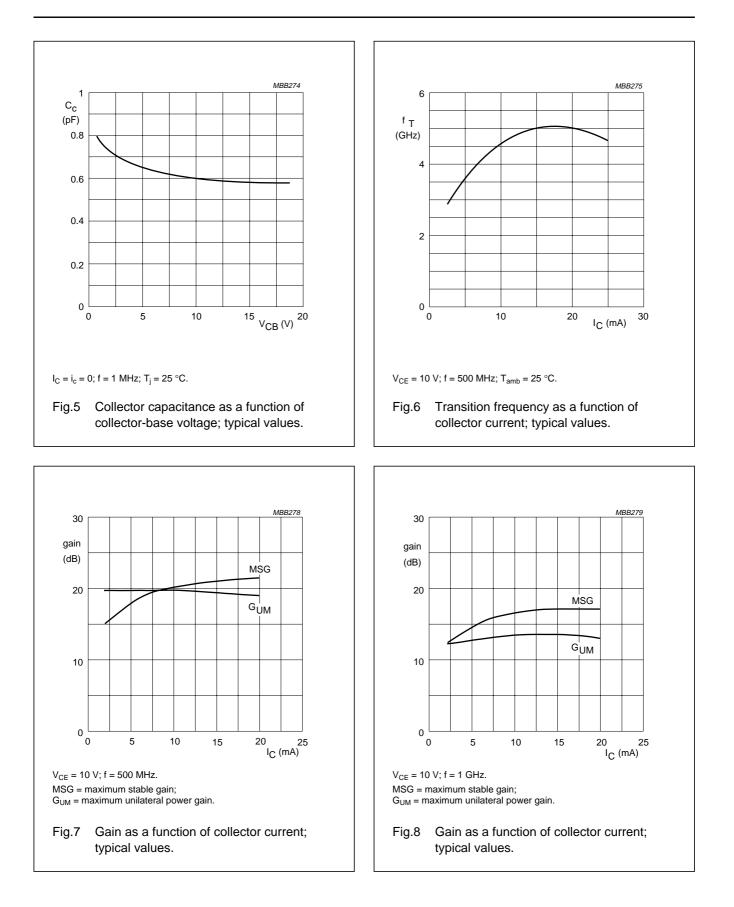
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and $G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} d\dot{B}$.

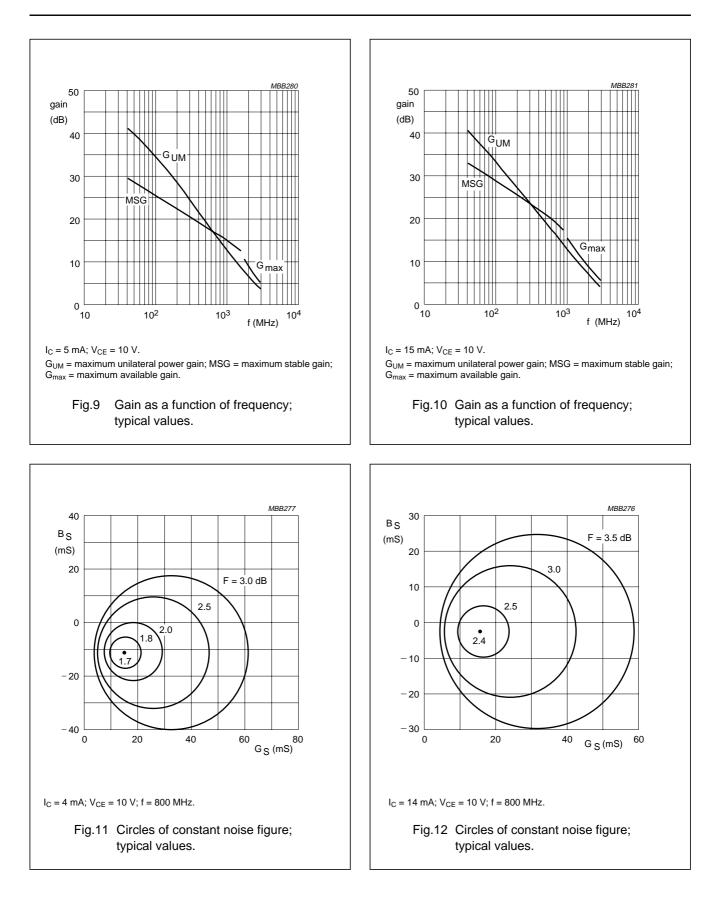
2. Measured on the same die in a SOT37 package (BFR90A).

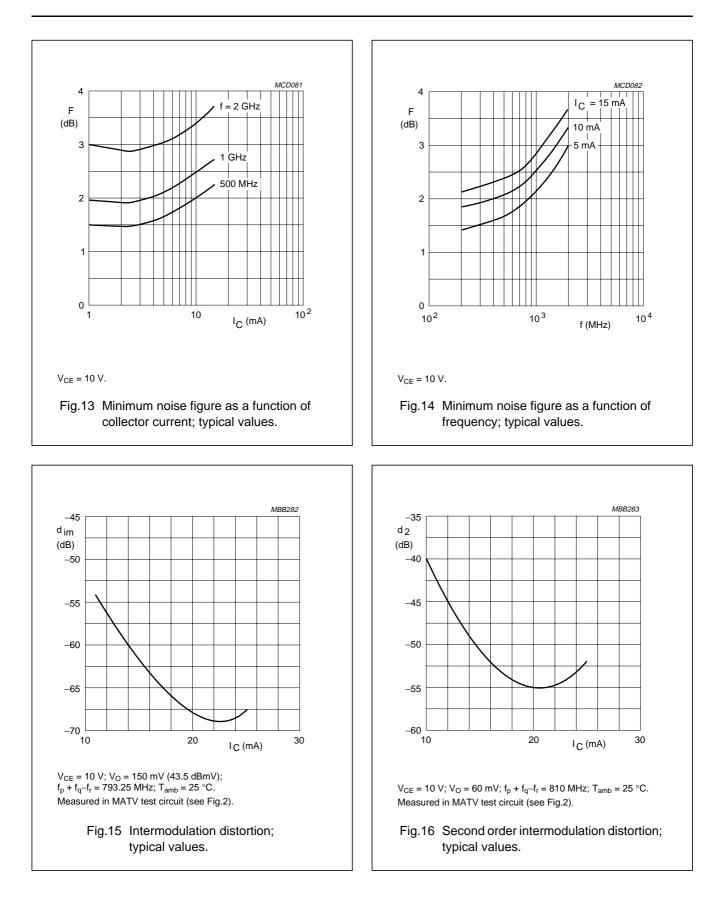
3. $d_{im} = -60 \text{ dB}$ (DIN 45004B); $I_C = 14 \text{ mA}$; $V_{CE} = 10 \text{ V}$; $R_L = 75 \Omega$; VSWR < 2; $T_{amb} = 25 \text{ °C}$ $V_p = V_O \text{ at } d_{im} = -60 \text{ dB}; f_p = 795.25 \text{ MHz};$ $V_q = V_O - 6 \text{ dB}; f_q = 803.25 \text{ MHz};$ $V_r = V_O - 6 \text{ dB}; f_r = 805.25 \text{ MHz};$ measured at $f_p + f_q - f_r = 793.25$ MHz.

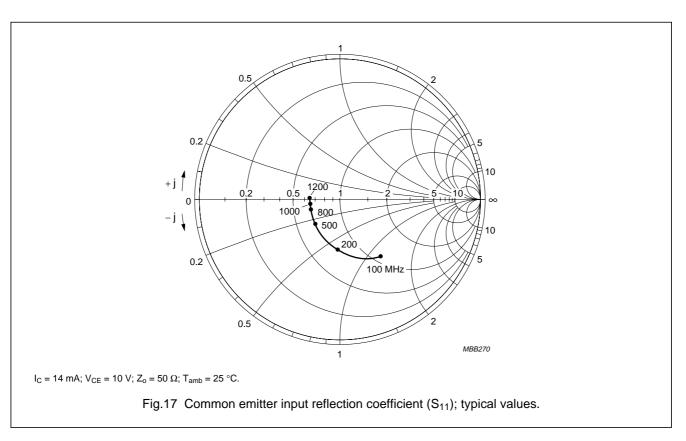
4. $I_C = 14 \text{ mA}; V_{CE} = 10 \text{ V}; R_L = 75 \Omega; \text{VSWR} < 2; T_{amb} = 25 \text{ °C}$ $V_p = 60 \text{ mV}$ at $f_p = 250 \text{ MHz}$; $V_q = 60 \text{ mV}$ at $f_q = 560 \text{ MHz}$; measured at $f_p + f_q = 810$ MHz.

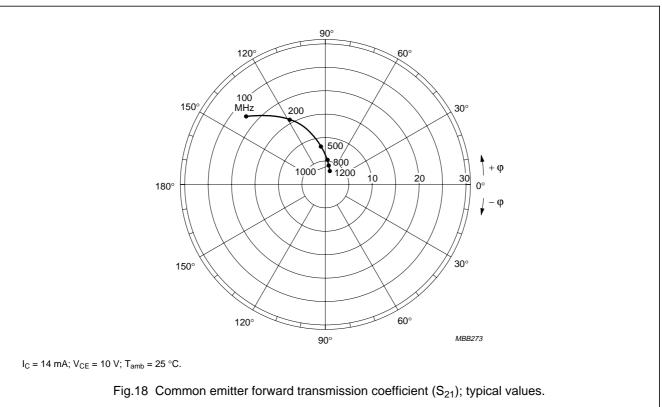


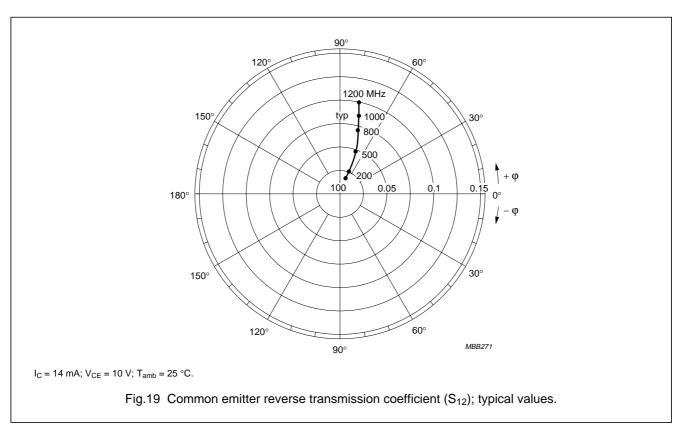


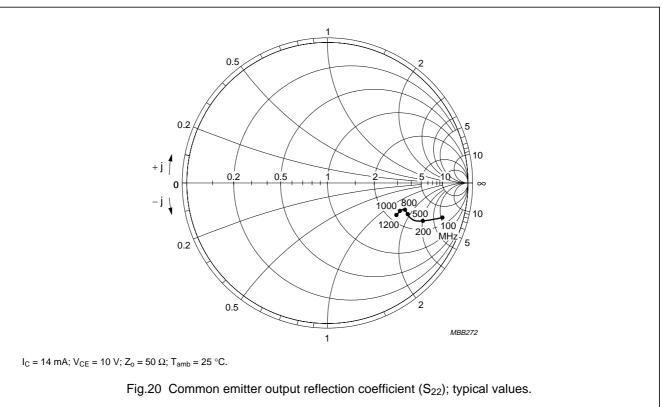










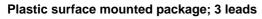


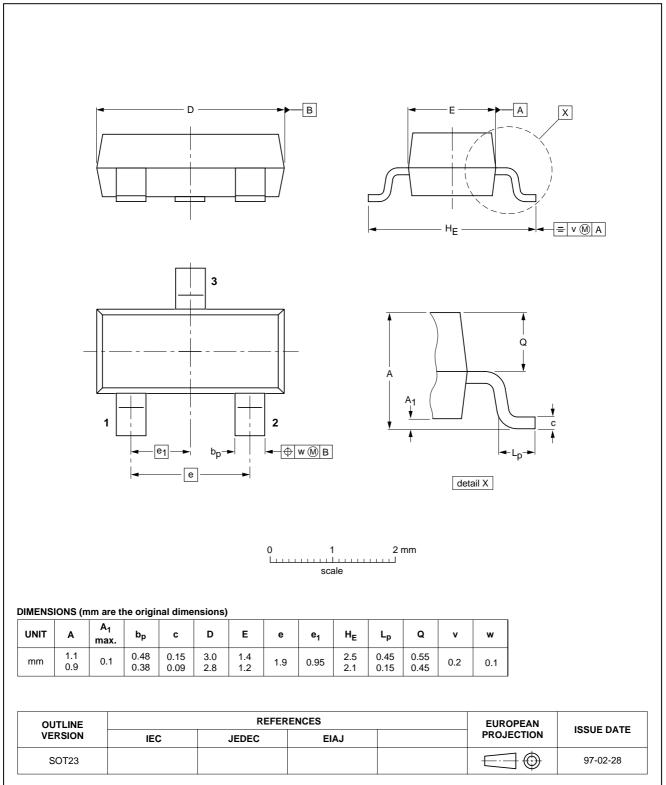
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SOT23

NPN 5 GHz wideband transistor

PACKAGE OUTLINE





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Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Revision history

Revision history				
Document ID	Release date	Data sheet status	Change notice	Supersedes
BFR92A_N_4	20090302	Product data sheet	-	BFR92A_N_3
Modifications:	 Fig.1 on pa 	ge 2; Figure note changed		
BFR92A_N_3	20080307	Product data sheet	-	BFR92A_2
BFR92A_2 (9397 750 02766)	19971029	Product specification	-	BFR92A_1
BFR92A_1	19950901	-	-	-

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